



Material Content Data Sheet



Sales Product Name				BTS133TC		Issued		27. September 2017	
MA#				MA000701082					
Package				PG-TO263-3-2		Weight*		1544.03 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	10.149	0.66	0.66	6573	6573	
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		197		
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	copper	7440-50-8	304.026	19.69	19.72	196904	197160	
wire	non noble metal	aluminium	7429-90-5	14.036	0.91	0.91	9091	9091	
encapsulation	organic material	carbon black	1333-86-4	7.180	0.46		4650		
	inorganic material	antimonytrioxide	1309-64-4	15.013	0.97		9723		
	plastics	brominated resin	-	16.971	1.10		10992		
	plastics	epoxy resin	-	124.020	8.03		80323		
	inorganic material	silicondioxide	60676-86-0	489.554	31.71	42.27	317063	422751	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.63	0.63	6254	6254	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		148		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	148	
glue	plastics	Polyimide	26023-21-2	0.432	0.03	0.03	280	280	
solder	noble metal	silver	7440-22-4	0.100	0.01		65		
	non noble metal	tin	7440-31-5	0.080	0.01		52		
	non noble metal	lead	7439-92-1	3.807	0.25	0.27	2465	2582	
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		355		
	inorganic material	phosphorus	7723-14-0	0.165	0.01		107		
	non noble metal	copper	7440-50-8	547.666	35.45	35.50	354698	355161	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com